

Nanomate V-Heart

For Silicon



Nanomate
V-Heart

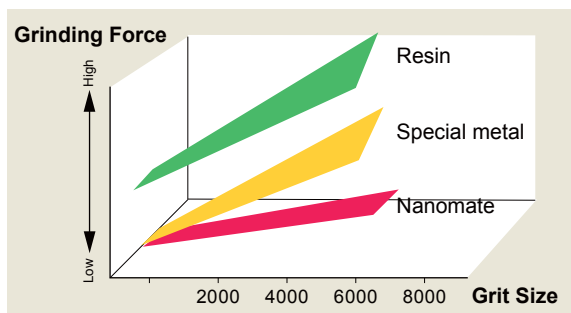
Suitable for rough grinding of deposited or sliced wafer

Strong diamond grit retention and high porosity vitrified bond, combined with a specially-shaped diamond layer, offers lower grinding force and improves grinding operations.

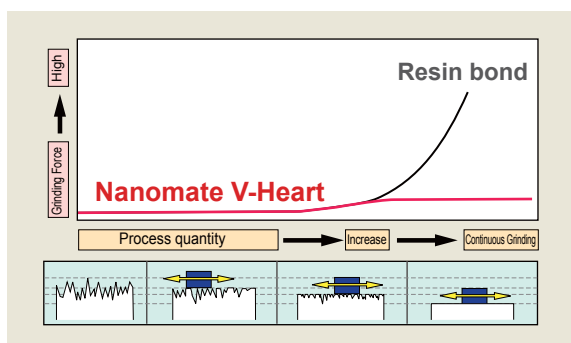
Achieves a flatness of less than $1\mu\text{m}$ on $\varnothing 300$ Si wafer and makes possible to grind hard-to-cut materials, including semi-conductor, electrics, and other materials.

□ Grinding Force

Low grinding forces result in reduction of each load applied on workpiece and grinding machine.



□ Grinding Force is 1/10 of resin bonding wheel



Nanomate Premium

For Silicon



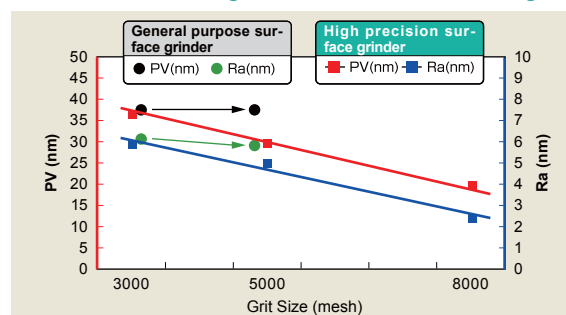
Nanomate
Premium

Suitable for mirror finish grinding of wafer and back side grinding of device wafer

Super-fine diamond grit and super-fine ceramics revolutionized the conventional wisdom with regard to grinding wheels. Application of both acquired material technology and production technology has allowed super-fine grinding.

Its effectiveness to reduce a grinding damaged layer of brittle material such as polish-reduction of $\varnothing 300\text{mm}$ silicon wafer and prevent cracks on a thin layer device wafer.

□ Relation between grit size and surface roughness



□ Grinding result by SD8000 Nanomate

